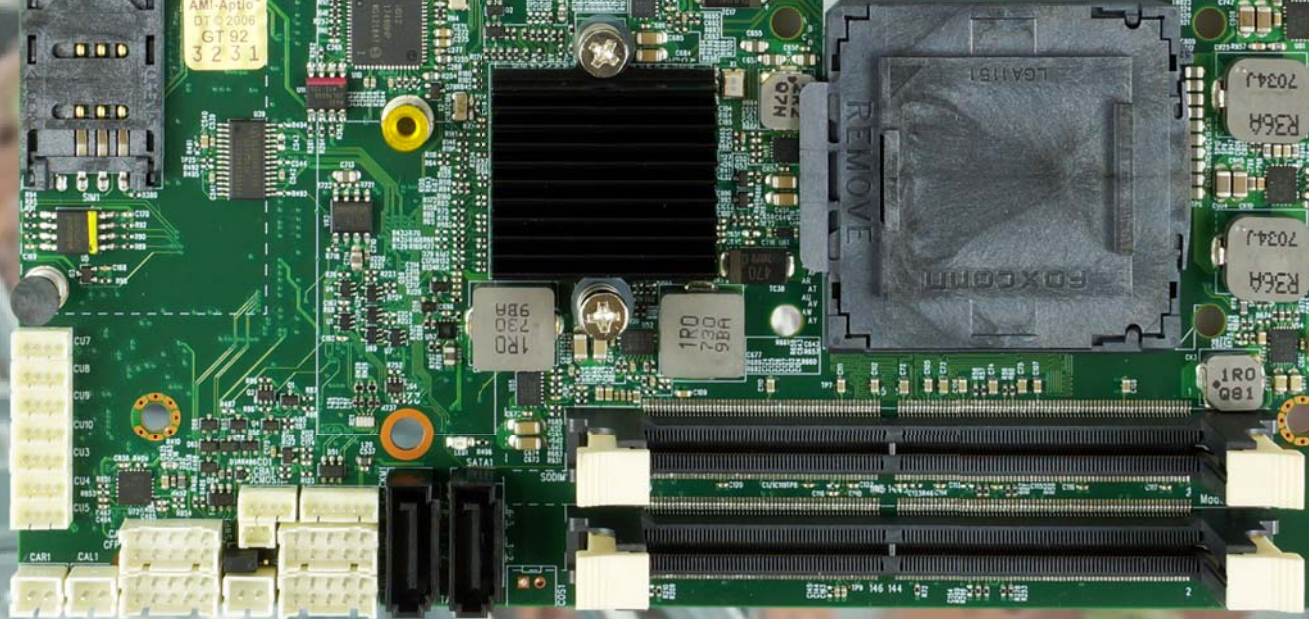


Flexible IO expansion with 3.5" Intel® Skylake-S / Kaby Lake-S Platform



31170HW Series



Flexible IO expansion with 3.5" Intel® Skylake-S / Kaby Lake-S Platform

LEX launches 3I170HW SBC with Intel® Skylake-S / Kaby Lake-S processor to give users fast, convenient and simplified solutions for industrial and embedded applications. This platform with all wafer IO design delivers high flexibility toward expanded functions and also provides user hassle-free solution of integrating the SBC board at various mechanical chassis for many reliability and mobility constrained embedded applications, such as Automation Control, Transportation, military and IP surveillance solutions.

Function MAP

LVDS Panel Inverter Power Select

LVDS Panel Power Select

COM2 Pin9 Select

COM1 Pin9 Select

+12V/+5V Output

DC-IN

COM2
COM1

CPU FAN

VGA

HDMI

LVDS

LVDS Power

LAN1

LAN2

LAN3

LAN4

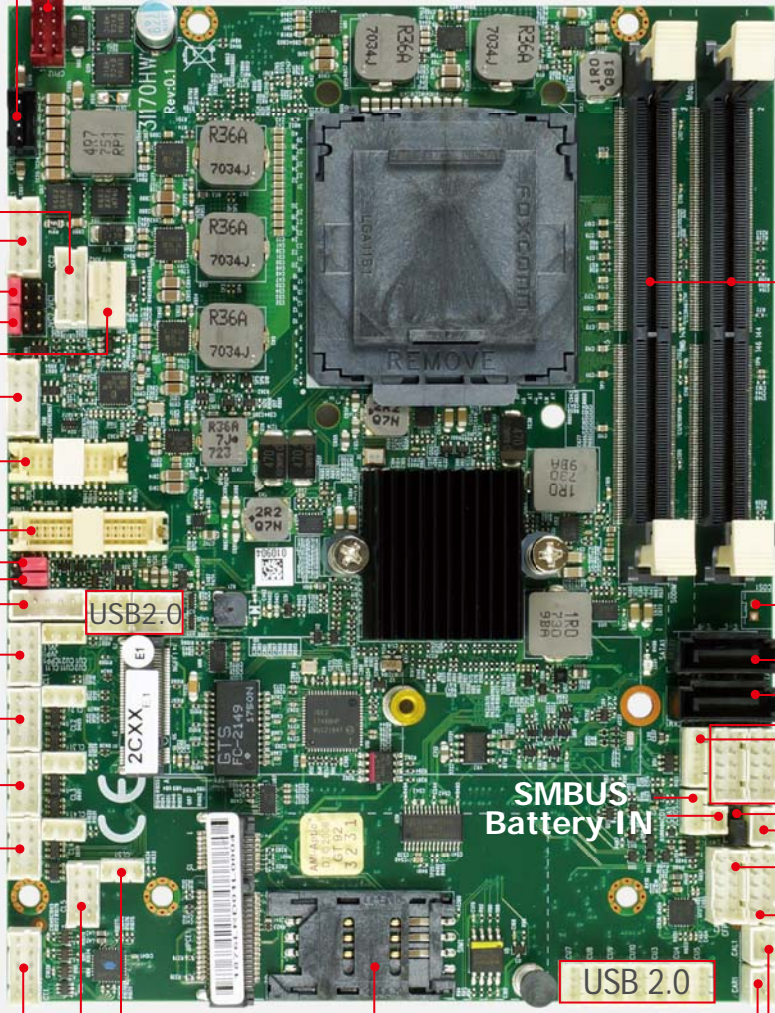
USB Touch

LAN5

LAN5 LED

SIM Socket

Audio AMP-R
Audio AMP-L



DDR4 SODIMM

Heater Power
(OEM)

SATA1

SATA1

PS2 KB/MS

4DIO

CMOS Data Clear

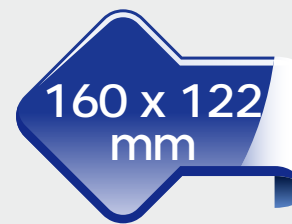
Power Switch

Line-in/Line-out/
Mic-in

Front Panel

SMBUS
Battery IN

USB 2.0



3I170HW

ideal solution for Industry 4.0 Applications

- Intel® Skylake-S / Kaby Lake-S i7/i5/i3 / Celeron CPU
- Intel Q170 chipset
- 2 x DDR4 SODIMM socket, max. up to 32GB
- Display Interface: HDMI, VGA & LVDS
- 5 x Intel (4 x I210 IT + 1 x I219LM) GbE, 1 x Mini PCIe, 1 x SIM
- 9 x USB (2 x USB 3.0/2.0 + 7 x USB 2.0), 2 x COM (RS232/422/485)
- 8DI/8DO, HD audio, 1 x M.2 B key, Touch Screen controller
- Wide Range DC IN +9~36V
- Operation temperature 0°C ~ 60°C

Data Sheet (PDF)